

PACKAGE STRUCTURE AND MANUFACTURING METHOD THEREOF

ABSTRACT OF THE DISCLOSURE

A package structure and a manufacturing method thereof are provided. The package structure includes an insulation layer, an electronic component and a lead frame unit. The electronic component is embedded within the insulation layer and includes plural conducting terminals. The lead frame unit is embedded within the insulation layer and includes a lead frame and a metallization layer. The metallization layer having a thickness more than 10 μm is disposed on at least a part of the lead frame and electrically connected with at least one of the plural conducting terminals of the electronic component.

Fig. 1